Dual Switching Diode, Common Anode

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Reverse Voltage	V _R	70	٧
Forward Current	IF	200	mA
Peak Forward Surge Current	I _{FM(surge)}	500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (T_A = 25°C)

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR- 5 Board	P_{D}	200	mW
(Note 1) T _A = 25°C			
Derate above 25°C		1.6	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	625	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C	P_{D}	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	- 55 to +150	ç

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

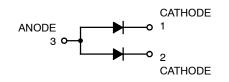
October, 2010 - Rev. 6

2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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MARKING DIAGRAM



SC-70 **CASE 419** STYLE 4



= Device Code = Date Code* = Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation may vary depending upon manufacturing location.

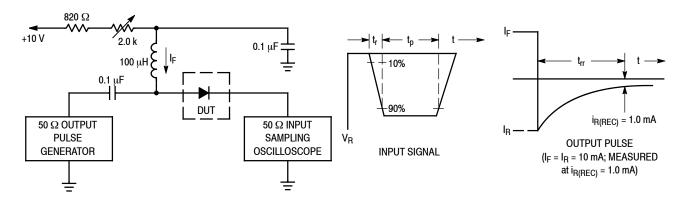
ORDERING INFORMATION

Device	Package	Shipping [†]
BAW56WT1G	SC-70 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Reverse Breakdown Voltage (I _(BR) = 100 μA)	V _(BR)	70	-	V		
Reverse Voltage Leakage Current $(V_R = 25 \text{ V}, T_J = 150^{\circ}\text{C})$ $(V_R = 70 \text{ V})$ $(V_R = 70 \text{ V}, T_J = 150^{\circ}\text{C})$	I _R	- - -	30 2.5 50	μΑ		
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	-	2.0	pF		
Forward Voltage (I _F = 1.0 mA) (I _F = 10 mA) (I _F = 60 mA) (I _F = 150 mA)	V _F	- - - -	715 855 1000 1250	mV		
Reverse Recovery Time (I _F = I _R = 10 mA, R _L = 100 Ω , I _{R(REC)} = 1.0 mA) (Figure 1)	t _{rr}	-	6.0	ns		



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA.

3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

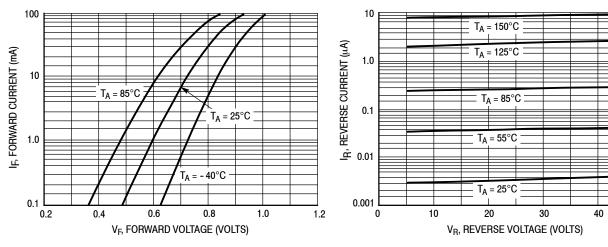


Figure 2. Forward Voltage

Figure 3. Leakage Current

50

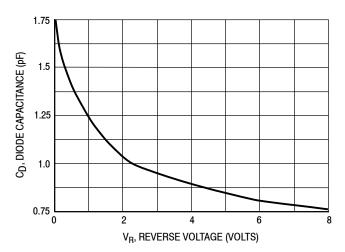
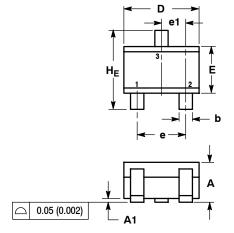


Figure 4. Capacitance

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE N





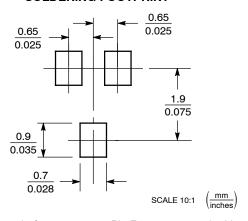
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095

STYLE 4: PIN 1.

CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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